

Product / Process Change Notification



N° 2018-136-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of an Additional Wafer Production Location at Infineon Technologies Dresden GmbH & Co. KG, Germany for CoolMOS™ 650V CFD and Harmonization of Halogen Free Mold Compound

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **19th November 2018**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Eckart Süner
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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► **Products affected:**

Please refer to attached affected product list 1_cip18136_a.xlsx

► **Detailed Change Information:**

Subject: Capacity expansion with 300mm wafer diameter for CoolMOS™ 650V CFD
Harmonization of PG-TO252-3 products from non-halogen free to halogen free mold compound, only applicable to these products:

Reason: Expansion of wafer production to assure continuity of supply and enable flexible manufacturing.
Infineon is standardizing to halogen free mold compound for all of its CoolMOS™ 650V CFD products in TO252-3 package to reduce complexity within the supply chain

Description:	<u>Old</u>	<u>New</u>
	<ul style="list-style-type: none"> ■ 200mm wafer diameter 	<ul style="list-style-type: none"> ■ 200mm wafer diameter ■ 300mm wafer diameter
	<ul style="list-style-type: none"> ■ Wafer fab location: Infineon Technologies Kulim Sdn Bhd, Malaysia Infineon Technologies Austria AG 	<ul style="list-style-type: none"> ■ Wafer fab location: Infineon Technologies Kulim Sdn Bhd, Malaysia Infineon Technologies Austria AG Infineon Technologies Dresden GmbH & Co. KG, Germany
	<ul style="list-style-type: none"> ■ Country of diffusion printed on barcode product label: Austria 	<ul style="list-style-type: none"> ■ Country of diffusion printed on barcode product label: Austria Germany
	<ul style="list-style-type: none"> ■ BE location Infineon Technologies (Malaysia) Sdn. Bhd. (200mm, halogen free) Tongfu Microelectronics Co., Ltd., China (200mm, non halogen free) 	<ul style="list-style-type: none"> ■ BE location Infineon Technologies (Malaysia) Sdn. Bhd. (200mm, halogen free) Tongfu Microelectronics Co., Ltd., China (300mm, halogen free)
	<ul style="list-style-type: none"> ■ Mold compound: Non halogen free MP8000 Halogen free KMC2110 	<ul style="list-style-type: none"> ■ Mold compound: Halogen free CEL9220 Halogen free KMC2110

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► Product Identification:

1. Internal traceability: Bau number, date code, lot number
2. External traceability:
 - a. Lot number printed on barcode product label
200mm: VExxxxxx
300mm: ZFxxxxxx
 - b. SP number
Please refer to "product identification by SP numbers"
3_cip18136_a

► Impact of Change:

No change to product quality and reliability as proven by product and wafer technology qualification
No change to existing product data sheet.
No change in package outline dimensions.

► Attachments:

- 1_cip18136_a: Affected product list
- 2_cip18136_a: Qualification report
- 3_cip18136_a: Product Identification by SP-Numbers

► Time Schedule:

- | | |
|-------------------------------|---|
| ■ Final qualification report: | available |
| ■ First samples available: | on request |
| ■ Intended start of delivery: | 2019-02-15 or earlier, depending on customer approval |

If you have any questions, please do not hesitate to contact your local Sales office.

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Sales name	SP number	OPN	Package
IPD65R1K4CFD	SP000953126	IPD65R1K4CFDBTMA1	PG-TO252-3
IPD65R420CFD	SP000891704	IPD65R420CFDBTMA1	PG-TO252-3
IPD65R420CFD	SP001117738	IPD65R420CFDATMA1	PG-TO252-3
IPD65R660CFD	SP000745024	IPD65R660CFDBTMA1	PG-TO252-3
IPD65R660CFD	SP001117748	IPD65R660CFDATMA1	PG-TO252-3
IPD65R950CFD	SP000953124	IPD65R950CFDBTMA1	PG-TO252-3
IPD65R950CFD	SP001117750	IPD65R950CFDATMA1	PG-TO252-3